# Intel® Server Board S1200v3RP Product Family Reliable, secure server performance for small business applications



Take your small business to the next level with a rack or pedestal server based on the Intel® Server Board S1200v3RP. Featuring support for the Intel® Xeon® processor E3-1200v4 product family, this suite of powerful, entry-level products expands deployment opportunities with select server features including management, storage, and enhanced processor graphics.

Select from four server boards:

**\$1200v3RPS**: lowest cost solution with basic server features

**\$1200v3RPL**: pedestal solution with optional management

**\$1200v3RPO**: rack optimized with I/O expansion

**S1200v3RPM**: rack optimized with I/O expansion and enhanced processor graphics support





#### Supports

- Intel® Xeon® processor E3-1200 v4
- 4 U-DIMMs at up to 1600MT/s
- Dual integrated Intel® Ethernet Controller
- Optional TPM Module
- For L, O and M boards only
  - Optional mezzanine connector
  - Optional Intel® Remote Management Module 4

# I/O Expansion Flexibility

# Rack or Pedestal Systems with Various Upgrade Features

For more information on Intel server solutions visit: intelserveredge.com

For more information on Intel server products visit: intel.com/go/serverproducts
For product specifications visit: ark.intel.com

For regulatory information visit: intel.com/support/motherboards/server/sb/CS-032524.htm



#### Intel® Server Board S1200v3RP Product Family Technical Specifications

Form Factor	1U rack: 1.75" x 17.24" x 21.8" 4U pedestal: 17.24" x 6.9" x 21.5"	
Server Board Included	\$1200v3RPS \$1200v3RPL \$1200v3RPO \$1200v3RPM	
<b>Processors Supported</b>	One Intel® Xeon® processor E3 1200 v4 product family, up to 95Ws	
Slot Types	S1200v3RPS/L 1 PCI Express* 3.0 x8 2 PCI Express 2.0 x4 1 PCI Express 2.0 x1 1 internal mezzanine connector x8 (L model only)	S1200v3RPO/M 1 PCI Express* 3.0 x8 1 internal or external mezzanine connector x8 OR 2 mezzanine connectors x4
Memory Capacity	4 U-DIMMs 1333 / 1600 ECC 32 GB max	
Drive Options	1U rack: 8 x 2.5" or 4 x 3.5" hot-swap HDDs 4U pedestal: 4 or 8 x 3.5" hot-swap HDDs Optional optical disk drive available for all systems	
System Cooling	Non-redundant cooling fans	
Power Supply Options	350W fixed, 450W or 460W AC Redundant PSU (Silver Efficiency)	
Module Upgrades	Intel® Trusted Platform Module For L, O and M boards only Intel® I/O Module Intel® Storage I/O Module Intel® Remote Management Module 4	

#### 1U rack

#### R1304RPSSFBN

4 x 3.5" fixed HDD 1 x 350W AC PSU

Intel Server Board S1200v3RPS

#### R1304RPOSHBN

4 x 3.5" hot-swap HDD 1 x 350W AC PSU Intel Server Board S1200v3RPO

## R1304RPMSHOR

4 x 3.5" hot-swap HDD 2 x 450W AC PSU Intel Server Board S1200v3RPM

### R1208RPOSHOR

8 x 2.5" hot-swap HDD 2 x 450W AC PSU Intel Server Board S1200v3RPO

R1208RPMSHOR

8 x 2.5" hot-swap HDD 2 x 450W AC PSU

Intel Server Board S1200v3RPM

#### 4U pedestal

#### P4308RPLSHDR

8 x 3.5" hot-swap HDD 2 x 460W AC PSU Intel Server Board S1200v3RPL

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